Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	79515	((copper Cu) with (W Mo)) ((cu copper) adj4 clad adj5 (invar Mo))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:06
L2	4346086	(((printed circuit wiring) adj4 board) carrier substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:07
L3	4217	1 with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:12
L4	39	(bend bending bended concave concaving dip dipping dipped concaved) with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:13
L5	27	(semicoductor assembly component electronic die chip dice ic (integrated adj circuit)) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:12
L6	9068	1 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:12
L7	2020	(semicoductor assembly component electronic die chip dice ic (integrated adj circuit)) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:13
L8	3466	(semiconductor assembly component electronic die chip dice ic (integrated adj circuit)) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 15:13

| L9 | 101 | (bend bending bended concave concaving dip dipping dipped concaved) same 8 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/15 15:13 |